2827
#6 letter 10/23/2 Butler

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Michihiko ICHINOSE

Appln. No.: 09/910,899

Confirmation No.: 3356

Filed: July 24, 2001

For: SEMICONDUCTOR DEVICE AND PACKAGING METHOD THEREOF

Docket No: Q63444

Group Art Unit: 2827

Examiner: Luan C. THAI

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

10/24/02 be confirmed

4T.

In response to the Office Action dated September 30, 2002 in which the Examiner has required a restriction, Applicant responds by electing Group I, *i.e.*, claims 1-19, drawn to a ~~method of making~~ semiconductor devices. This election is made without prejudice to the filing of a divisional application directed to the non-elected claims.

Prompt and favorable action on the elected claims is now respectfully requested.

Respectfully submitted,

Howard L. Bernstein
Registration No. 25,665

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Date: October 18, 2002

2827

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#9 Electi

1-13-03 L. Sprue

In re application of

Michihiko ICHINOSE

Appln. No.: 09/910,899

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Examiner: Luan C. THAI

For: SEMICONDUCTOR DEVICE AND PACKAGING METHOD THEREOF

RESPONSE TO ELECTION OF SPECIES REQUIREMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated November 18, 2002 in which the Examiner has required an election of species, Applicant responds by electing with traverse Embodiment 1, Figures 5B. Claims 1-5 and 13 read on the elected species.

Applicant submits that Claims 1-3 are generic. The table below fully supports applicants position as to the generic nature of claims 1-3.

	Fig. 5A & 5B	Fig. 7A & 7B	Fig. 9A-9E	Fig. 8A & 8B
first resin package	11 : first resin sealed package	11	11	11 / 11': first resin sealed package
semiconductor chip	3 : semiconductor chip	3	3	3 / 3' : semiconductor chip
chip electrode	15 : electrode	15	15	15 / 15': electrode
first resin	7 : first sealing resin	7	7	7 / 7' : first sealing resin
first package electrode	4 (101+102) : electrode	4 (101+102)	94 (92+93) : wiring electrode	4 / 4' (81+82) : electrode
first electrode region	101 : mounting area	101	93 : mounting area	101 / 81 : mounting area
second electrode region	102 : testing area	102	92 : testing area	102 / 82 : testing area
mounted object	2 : mounting substrate (21 : terminal)	2 (21)	2 (21)	11' (4') / 14 : lead frame
wiring	6 : second boning wire	6	6	6 / 6' : second bonding wire

US COMMISSIONER OF PATENTS
Application Number 09/910,899

Prompt and favorable action on the elected claims are now respectfully requested.

Respectfully submitted,

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WASHINGTON OFFICE

23373
PATENT TRADEMARK OFFICE

Howard L. Bernstein
Registration No. 25,665

Date: December 18, 2002